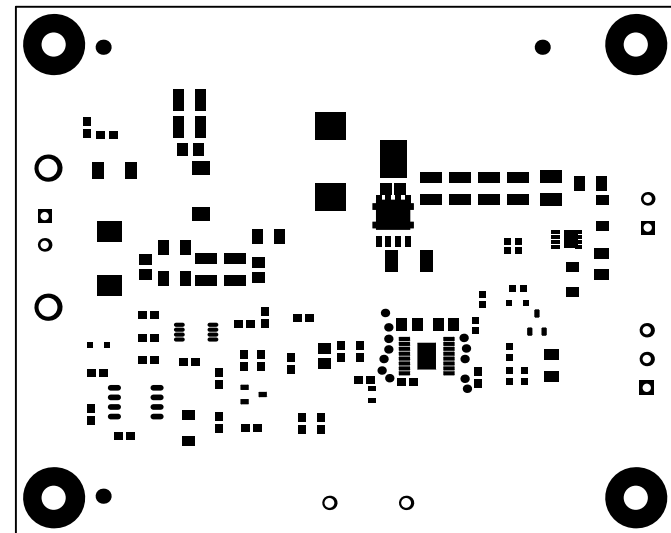
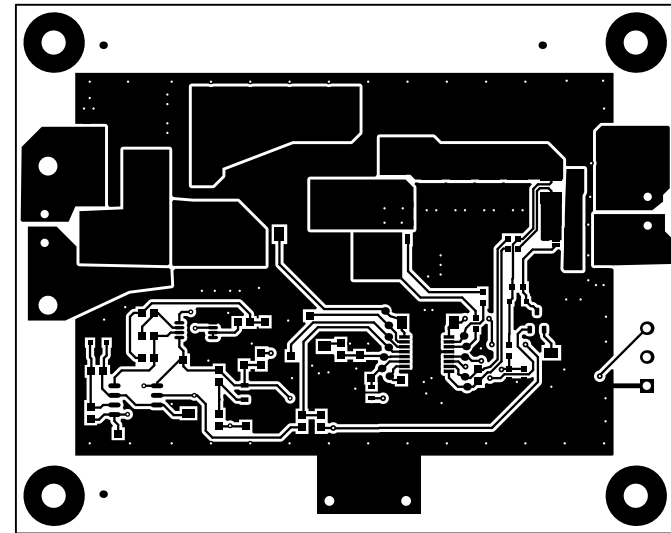


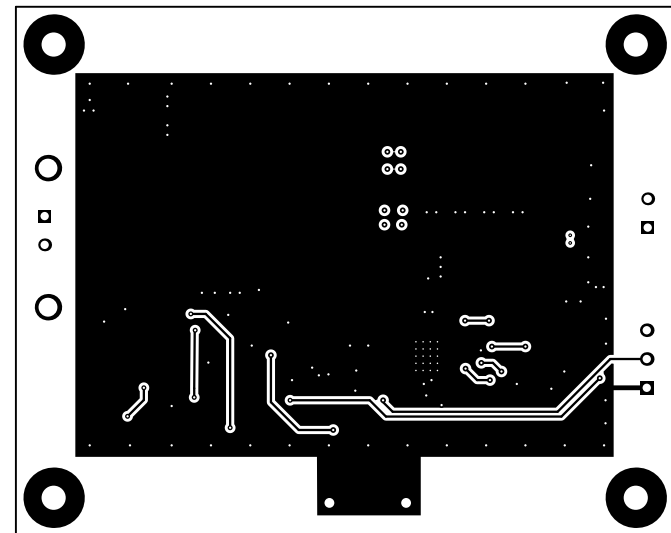
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01382	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 2/10/2017 12:47:08 PM	TEXAS INSTRUMENTS	



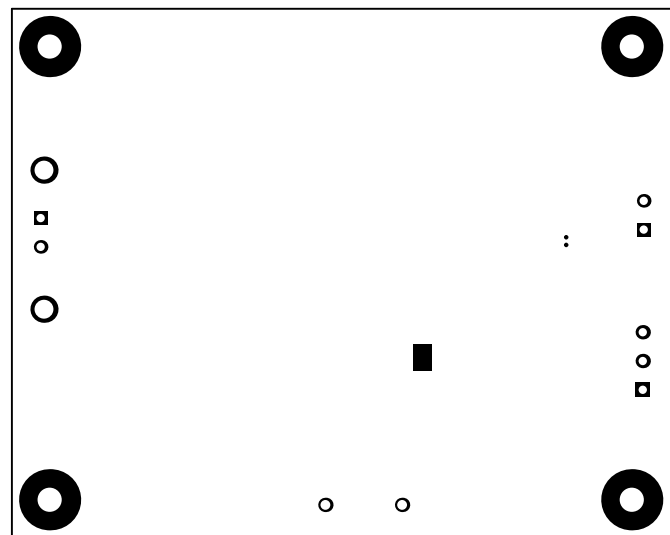
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01382	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 2/10/2017 12:47:09 PM	TEXAS INSTRUMENTS	



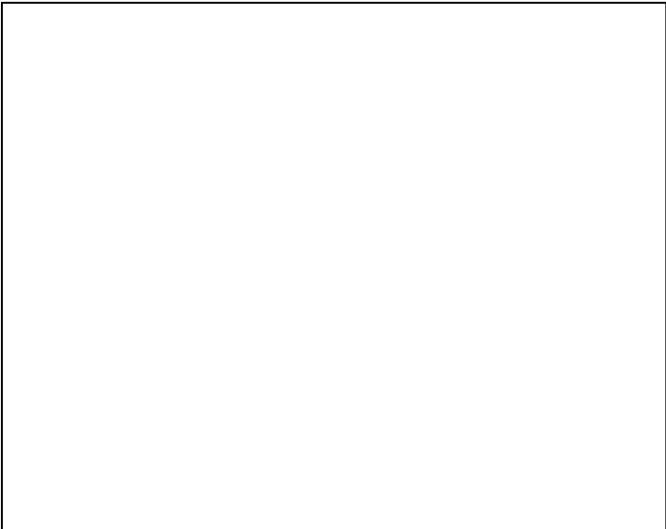
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01382	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 2/10/2017 12:47:11 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01382	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 2/10/2017 12:47:12 PM	TEXAS INSTRUMENTS	

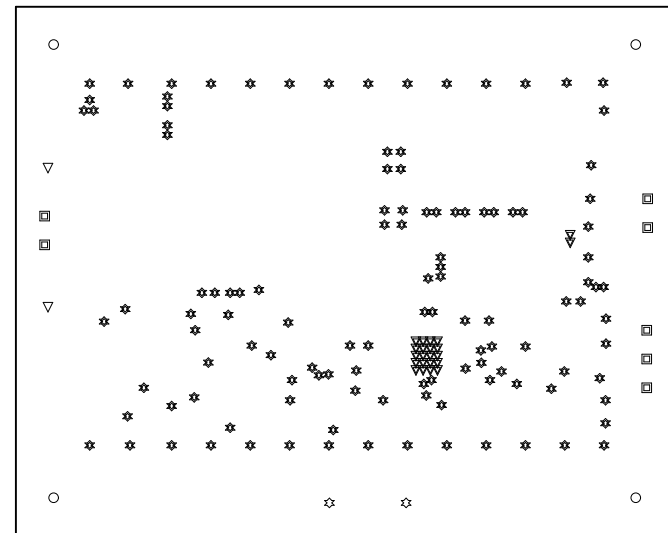


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01382	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 2/10/2017 12:47:14 PM	TEXAS INSTRUMENTS	

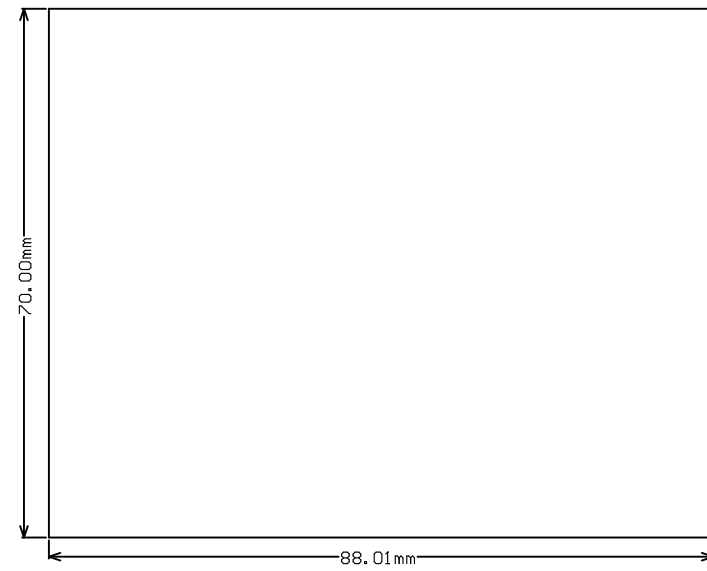


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01382	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 2/10/2017 12:47:15 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
▽	22	0.200mm (7.87mil)	PTH	Round	Top Layer - Bottom Layer	
*	118	0.305mm (12.00mil)	PTH	Round	Top Layer - Bottom Layer	
■	7	1.100mm (43.31mil)	PTH	Round	Top Layer - Bottom Layer	
☆	2	1.300mm (51.18mil)	PTH	Round	Top Layer - Bottom Layer	
▽	2	2.500mm (98.43mil)	PTH	Round	Top Layer - Bottom Layer	
○	4	3.200mm (125.98mil)	PTH	Round	Top Layer - Bottom Layer	
	155 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01382	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 2/10/2017	12:47:16 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01382	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 2/10/2017 12:47:18 PM	TEXAS INSTRUMENTS	

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